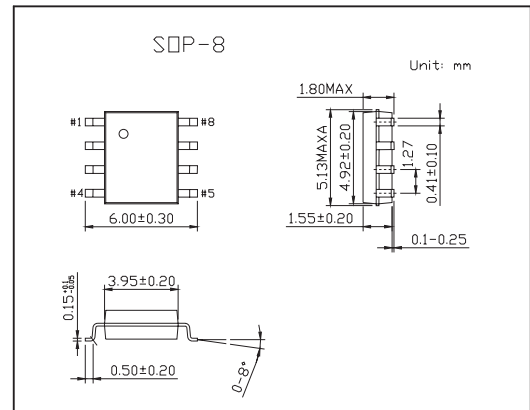
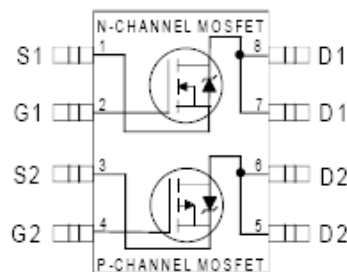


HEXFET[®] Power MOSFET

KRF7343

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Fully Avalanche Rated



■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	55	-55	V
Continuous Drain Current, $V_{GS}@10V$, $T_a = 25^\circ\text{C}$	I_D	4.7	-3.4	A
Continuous Drain Current, $V_{GS}@10V$, $T_a = 70^\circ\text{C}$	I_D	3.8	-2.7	
Pulsed Drain Current *1	I_{DM}	38	-27	
Power Dissipation @ $T_a = 25^\circ\text{C}$ *5	P_D	2.0		W
Power Dissipation @ $T_a = 70^\circ\text{C}$ *5		1.3		
Gate-to-Source Voltage	V_{GS}	± 20		V
Single Pulse Avalanche Energy *3	E_{AS}	72	114	mJ
Avalanche Current	I_{AR}	4.7	-3.4	A
Repetitive Avalanche Energy	E_{AR}	0.20		mJ
Peak Diode Recovery dv/dt *2	dv/dt	5.0	-5.0	V/ns
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150		$^\circ\text{C}$
Maximum Junction-to-Ambient *5	$R_{\theta JA}$	62.5		$^\circ\text{C/W}$

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel $I_{SD} \leq 4.7\text{A}$, $di/dt \leq 220\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$

P-Channel $I_{SD} \leq -3.4\text{A}$, $di/dt \leq -150\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$

*3 N-Channel Starting $T_J = 25^\circ\text{C}$, $L = 6.5\text{mH}$ $R_G = 25\ \Omega$, $I_{AS} = 4.7\text{A}$.

P-Channel Starting $T_J = 25^\circ\text{C}$, $L = 20\text{mH}$ $R_G = 25\ \Omega$, $I_{AS} = -3.4\text{A}$.

*5 Surface mounted on FR-4 board, $t \leq 10\text{sec}$.

*4 Pulse width $\leq 300\ \mu\text{s}$; duty cycle $\leq 2\%$.

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250 \mu A$	N-Ch	55		V
		$V_{GS} = 0V, I_D = -250 \mu A$	P-Ch	-55		
Breakdown Voltage Temp. Coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	$I_D = 1mA, \text{Reference to } 25^\circ C$	N-Ch	0.059		V/°C
		$I_D = -1mA, \text{Reference to } 25^\circ C$	P-Ch	0.054		
Static Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 4.7A^*1$	N-Ch	0.043	0.050	Ω
		$V_{GS} = 4.5V, I_D = 3.8A^*1$		0.056	0.065	
		$V_{GS} = -10V, I_D = -3.4A^*1$	P-Ch	0.095	0.105	
		$V_{GS} = -4.5V, I_D = -2.7A^*1$		0.150	0.170	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch			V
		$V_{DS} = V_{GS}, I_D = -250 \mu A$	P-Ch			
Forward Transconductance	g_{fs}	$V_{DS} = 10V, I_D = 4.5A^*1$	N-Ch			S
		$V_{DS} = -10V, I_D = -3.5A^*1$	P-Ch			
Drain-to-Source Leakage Current	I_{DSS}	$V_{DS} = 55V, V_{GS} = 0V$	N-Ch		2.0	μA
		$V_{DS} = -55V, V_{GS} = 0V$	P-Ch		-2.0	
		$V_{DS} = 55V, V_{GS} = 0V, T_J = 55^\circ C$	N-Ch		25	
		$V_{DS} = -55V, V_{GS} = 0V, T_J = 55^\circ C$	P-Ch		-25	
Gate-to-Source Forward Leakage	I_{GSS}	$V_{GS} = \pm 20V$	N-Ch		± 100	nA
			P-Ch		± 100	
Total Gate Charge	Q_g	N-Channel $I_D = 4.5A, V_{DS} = 44V, V_{GS} = 10V$	N-Ch	24	36	nC
Gate-to-Source Charge	Q_{gs}		P-Ch	26	38	
			N-Ch	2.3	3.4	
Gate-to-Drain ("Miller") Charge	Q_{gd}		P-Channel $I_D = -3.1A, V_{DS} = -44V, V_{GS} = -10V$	P-Ch	3.0	
		N-Ch	7.0	10		
Turn-On Delay Time	$t_{d(on)}$	N-Channel $V_{DD} = 28V, I_D = 1.0A, R_G = 6.0 \Omega$	N-Ch	8.3	12	ns
			P-Ch	14	22	
Rise Time	t_r	$R_D = 16 \Omega$ P-Channel	N-Ch	3.2	4.8	
			P-Ch	10	15	
Turn-Off Delay Time	$t_{d(off)}$	$V_{DD} = -28V, I_D = -1.0A, R_G = 6.0 \Omega$ $R_D = 16 \Omega$	N-Ch	32	48	
			P-Ch	43	64	
Fall Time	t_f		N-Ch	13	20	
			P-Ch	22	32	
Input Capacitance	C_{iss}	N-Channel $V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$	N-Ch	740		pF
			P-Ch	690		
Output Capacitance	C_{oss}	P-Channel	N-Ch	190		
			P-Ch	210		
Reverse Transfer Capacitance	C_{rss}	$V_{GS} = 0V, V_{DS} = -25V, f = 1.0MHz$	N-Ch	71		
			P-Ch	86		

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	Is		N-Ch		2.0	A
			P-Ch		-2.0	
Pulsed Source Current (Body Diode) *2	ISM		N-Ch		38	
			P-Ch		-27	
Diode Forward Voltage	VSD	TJ = 25°C, Is = 2.0A, VGS = 0V*1	N-Ch	0.70	1.2	V
		TJ = 25°C, Is = -2.0A, VGS = 0V*1	P-Ch	0.80	-1.2	
Reverse Recovery Time	trr	N-Channel TJ = 25°C, IF = 2.0A, di/dt = 100A/μs*1	N-Ch	60	90	ns
			P-Ch	54	80	
Reverse RecoveryCharge	Qrr	P-Channel TJ=25°C,IF=-2.0A,di/dt=-100A/μs*1	N-Ch	120	170	nC
			P-Ch	85	130	

*1 Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.

*2 Repetitive rating; pulse width limited by max. junction temperature.